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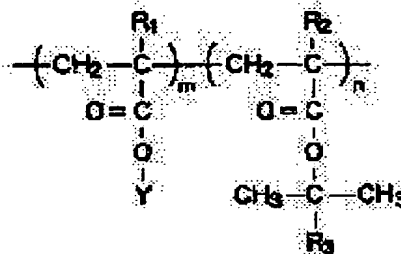
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(54) RADIATION SENSITIVE MATERIAL AND PATTERN FORMING METHOD

(57)Abstract:

PURPOSE: To provide a radiation sensitive material which can be used in lithography taking an exima laser as an exposure source, and which has high sensitivity and excellent adhesive property as well as excellent transparency and etching resistance by forming the material by a specified copolymer and a material caused to generate an acid by radiation exposure.

CONSTITUTION: A radiation sensitive material is formed by a copolymer expressed by the formula and a material caused to generate an acid by radiation exposure. In the formula, R1 and R2 respectively indicate CH3 or H, and at least one of R1 and R2 is H. R3 indicates an alkyl group, and Y indicates the alicyclic series. The unit structure having the alicyclic series in the copolymer is preferably 40-70mol%. If the composition is under 40mol%, satisfactory dry etching resistance can not be obtained, and if it exceeds 70mol%, t-butyl unit which is photosensitive is few so that patterning is difficult.



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